标准&定制开关连接器产品制造商

DONG GUAN XI BANG ELECTRONICS CO., LTD.

Switch Connector

规　　格　　书

SPECIFICATION

CUSTOMER NAME	客户名称：	
CUSTOMER NO.	客户编号：	
SERIES	系　　列：	CS系列插座
MODEL NO.	型　　号：	XB-series
DRAWING NO.	图 形 号：	CS Series Sockets

If specification of this product meets your request, please confirm all the items of it and return to us with signature and stamp, it will be basis of our production and record. Thanks your cooperation in advance!

若此产品规格符合贵司要求，敬请确认此规格书内所有项目

并签名和盖章后回传给我司，以作我司产品制作之

依据和存档之用，多谢合作！

EXAMINE & APPROVAL 审批	
APPROVE 接受	NOT APPROVE 不接受
SIGNATURE 签署　　STAMP盖章　　DATE日期	

PREPARED BY.制表人	CHECKED BY.校对	APPROVED BY.审核	APPROVAL BY. 批准
研发部 戴海明 2022. 06. 08	品质部 黄自清 2022. 06. 08	工程部 庞军 2022. 06. 08	总经办 吴量 2022. 06. 08

东莞市溪榜电子有限公司

Dong guan Xi Bang Electronics Co., Ltd

地址：广东省东莞市黄江镇合路工业区

Address:He Lu Industrial Zone, Huangjiang Town ,Dongguan City, Guangdong Province

Tel: (0769)82055138/82056828

Fax:(0769)83663452

邮箱：admin@alspr.com　switch@alspr.com

http://www.alspr.cn/　http://www.alspr.com/

Dong Guan XB ElectronicsCo.,Ltd

AccountNumber: 705540238

BankName: CitibankN.A.,HongKongBranch

Country/Region:Hong Kong

BankCode:006

BankAddress: 3GardenRoad,Central,Hong Kong

SWIFT/BIC: CITIHKHX(CITIHKHXXXX*If11charactersare required)

MAiL：HK@ALPSR.CN　XB@ALPSR.CN　XB@ALPSR.COM

Quality core! Afterburner for Made in China!

东莞市溪榜电子有限公司
DONG GUAN XI BANG ELECTRONI CS CO., LTD.

ENGINEERING DEPT.		PRODUCT SPECIFICATION	SPEC.NO.: SPCS037B
REVISIONS	ECNT120150	For CS76 Series Connector System	PAGE: 1 / 7

1. SCOPE:
This specification contains the test requirement of subject DIP socket when tested under the condition and below standards base on Xi Bang connector test procedure

2. APPLICABLE STANDARDS:
MIL - STD - 202 Methods for test of connectors for electronic equipment
EIA - 364 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CS76 series

4. SHAPE, CONSTRUCTION AND DIMENSIONS
See attached drawings

5. MATERIALS
See attached drawings

6. ACCOMMODATED P.C.BOARD
6.1 Thickness: 1.6 mm (.063″)
6.2 P.C. Board Layout: See attached drawings

REVIEWED : XIE.BING.XIN APPROVED : HE.LONG.FEI VERIFIED : PANG.DONG .

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		0.5A (per pin) 50V AC (per pin)
7.2	Contact resistance	Solder connectors on PCB and mate them together, measure by applying closed circuit current of 100mA maximum at open circuit voltage of 20mV maximum. EIA-364-23B [Reference to Figure 1]	Less than 55 mΩ Max. (Initial) Less than 20 mΩ Max change allowed. (Final)
7.3	Dielectric strength	When applied AC 300 V 1minute between adjacent terminal EIA-364-20C	No change (Current leakage: 1 mA Max.)
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground EIA-364-21C	More than 500 MΩ (Initial) More than 500 MΩ (Final)

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Mating /Un mating Force	Card mating/un mating sequence: a) Insert the card at the angle specified by the manufacture. b) Rotate the card into position. c) Reverse the installation sequence to un mating. Operation Speed: 25.4mm per minute. Measure the force required to mate/un mate connector. EIA-364-13 Method A [Reference to Figure 3]	60 cycles Mating Force: 20N (2.039 kgf) Max. Un mating Force: 25N (2.548 kgf) Max.
8.2	Durability	The sample should be mounted in the tester and fully mate and unmated the rate of 25.4mm per minute. EIA-364-09	60 cycles No evidence of physical damage.
8.3	Vibration	2 hours in each of 3 mutually perpendicular directions. Both mating halves should be rigidly fixed so as not to contribute to the relative motion of one contact against another. The method of fixturing should be detailed in the test report. Sinusoidal curve, Test condition I EIA-364-28	No electrical discontinuity greater than 1 μ sec shall occur. No evidence of physical damage.

	ITEM	TEST CONDITION	REQUIREMENT
8.4	Mechanical Shock	50G, 11ms Half sine No. of Drops: 3 drops each to normal and reversed directions of X, Y, and Z axes, totally 18 drops. EIA-364-27B	No electrical discontinuity greater than 1 μ sec shall occur. No evidence of physical damage.
8.5	Contact Retention Force	Place a connector on the push-pull machine, then apply a force on a contact head and push the contact to the opposite direction of the contact insertion at the speed of 25±3mm /min. Measure the force when the contact dislodges from insulator.	0.5N(0.05kgf)/pos. Min.

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Mate connectors, measure the temperature rise at rated current after 0.5A/Power contact. The temperature rise above ambient shall not exceed 30° C the ambient condition is still air at 25° C . EIA-364-70 Method 2 [Reference to Figure 2]	30° C max.
9.2	Humidity Temperature cycling	Mated Connector. Initial measurement, cold shock and vibration. Cycle the connector between 25±3°C at 80±3% RH and 65±3°C at 50±3% RH. Ramp times should be 0.5 hour and dwell times should be 1.0 hour. Dwell times start when the temperature and humidity have stabilized within the specified levels. Perform 24 such cycles. EIA-364-31,method Ⅲ	No evidence of physical damage. Contact resistance: 20 mΩ max change allowed (Final)
9.3	Thermal Shock	Mated Connector. EIA-364-32,test condition Ⅰ, 10 cycles	No evidence of physical damage. Contact resistance: 20 mΩ max change allowed (Final)
9.4	Temperature Life	Mated Connector, 105° C , 120 hours EIA-364-17,method A	No evidence of physical damage. Contact resistance: 20 mΩ max change allowed (Final)

	ITEM	TEST CONDITION	REQUIREMENT
9.5	Thermal Disturbance	Cycle the connector between 15±3°C and 85±3°C, as measured on the part. Ramp times should be a minimum of 2°C per minute, and dwell times should insure that the contacts reach the temperature extremes (a minimum of 5 minutes).Humidity is not controlled. Perform 10 such cycles.	No evidence of physical damage. Contact resistance: 20 mΩ max change allowed (Final)
9.6	Solder ability	Soldering time: 10 second Soldering pot: 245°C	Minimum: 95% of immersed area
9.7	Resistance to soldering heat	Pre-heat: 150～215° C, 30～120 sec. Reflow: 230° C Min, 20 sec Min. Peak temp: 260° C Max, 10 sec Max. [Reference to Figure 4]	No evidence of physical damage.
9.8	Salt Spray	Temperature: 35 ± 3°C Solution: 5 ± 1% Spray time: 48 ± 4 hours (Stamping before plated) Spray time: 24 ± 4 hours (Stamping after plated) Mate connectors and expose to the following salt mist conditions. Upon completion of the exposure period, salt deposits shall be removed by a gentle wash or dip in running water and dried naturally, after which the specified measurements shall be performed. The specimens shall be suspended from the top using waxed twine, string or nylon thread. The test only define the plating area, without plating area (as copper cross section) will not be defined. (EIA 364-26B / MIL-STD-202 Method 101)	Appearance: No damage on function Contact resistance: Less than twice of initial

10. OPERATING TEMPERATURE RANGE: -40 to + 80° C

11. Test Sequence

Test Item		Test Group												
		A	B	C	D	E	F	G	H	I	J	K	L	M
1	Examination of Product	1,3	1,7	1,5	1,5	1	1,5	1,7	1,5	1,5	1,5	1,3	1,3	1,3
2	Low level contact resistance		2,6	2,4	2,4		2,4		2,4	2,4	2,4			
3	Dielectric withstanding voltage							2,5						
4	Insulation Resistance							3,6						
5	Temperature rise	2												
6	Mating/Un mating Force		3,5											
7	Durability		4											
8	Vibration			3										
9	Mechanical Shock				3									
10	Contact Retention Force					2								
11	Humidity Temperature Cycling						3	4						
12	Thermal Shock								3					
13	Temperature Life									3				
14	Thermal Disturbance										3			
15	Reflow Soldering Heat Resistance											2		
16	Solder ability												2	
17	Salt Spray													2
Quantities of Samples		5	5	5	5	5	5	5	5	5	5	5	5	5

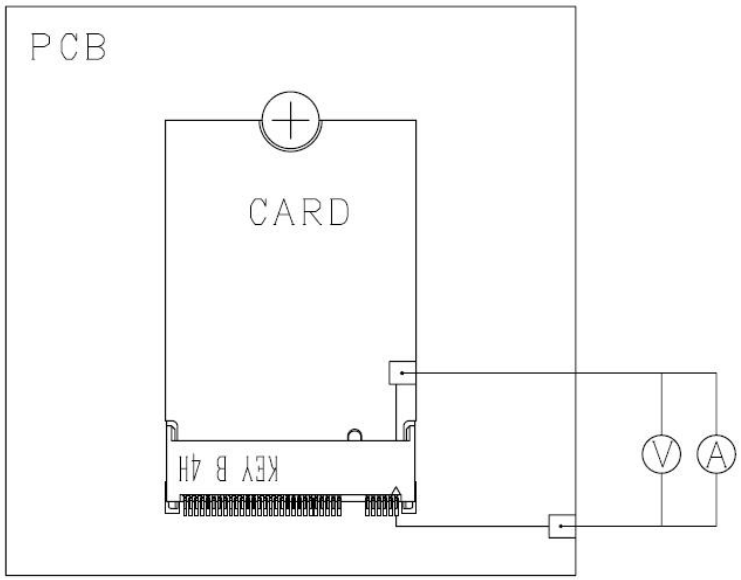

Figure 1

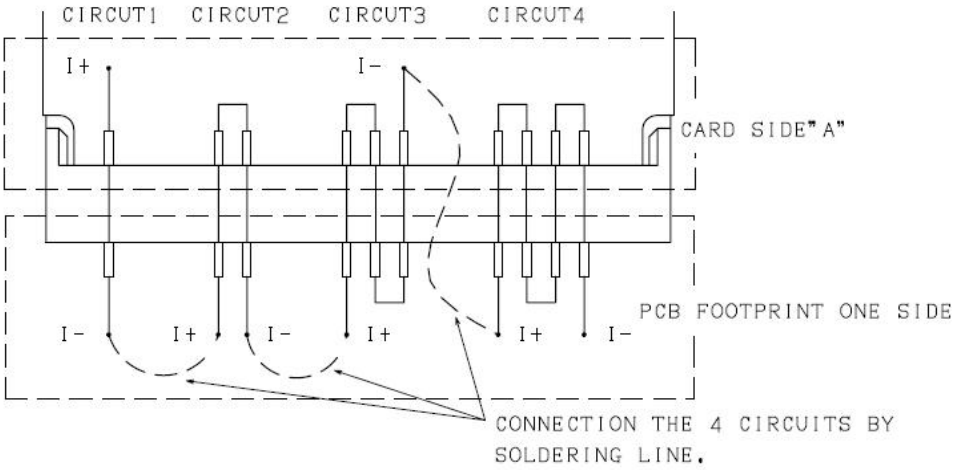

Figure 2

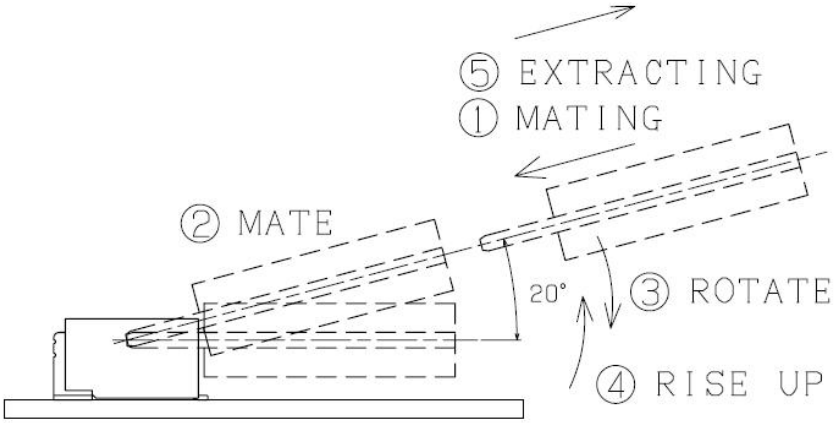

Figure 3

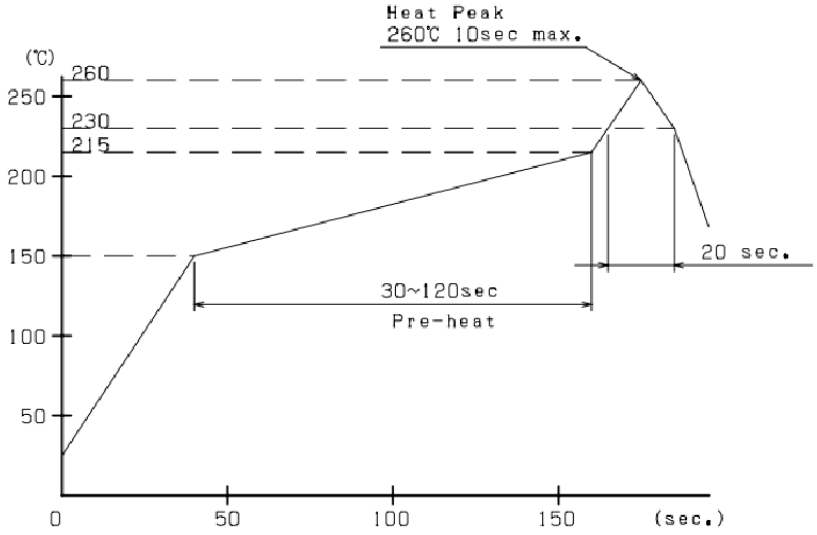

Figure 4